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AGS Division Technical Note
No. 208

AGS STANDARD PACKAGE FOR ELECTRONIC CONTROLS

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Introduction

The computer control and data acquisition systems in the AGS and its surrounding complex operate under what only can be defined as hostile conditions for electronics. Briefly, these conditions can be described as: 1) mechanical stress, such as heat, moisture, and vibration, 2) electrical stress, such as from large magnetic fields, and electrical noise, and 3) general physical abuse due to constant activity in the areas where equipment is located. With these problems in mind, a study group was formed to define a standard package for electronic controls that would tolerate the above conditions as much as possible, still meet the needs of the controls medium, and be of use to other, non-controls specialists who may have similar packaging problems. The following document is a short description of the packaging scheme which evolved as a direct result of the study group's deliberations.

"Package" Description

1. The Chassis

The package consists of a 19" rack mountable, 0.063" thick aluminum chassis, approximately 21" long, 17" wide and 11-1/2" high. It is designed to be mounted on slides for ease of service to the electronics contents. One can see from the information in Appendix 4 that the

difference in the amount of rf shielding by either aluminum or steel when proper design is used is not enough to compensate for the reduced aluminum weight and the ease of working aluminum. Physically, the chassis is divided into two compartments by a bulkhead, with the front compartment containing power supplies for the electronics which are contained in the rear compartment. If a user has an application that demands more space than the electronic compartment contains, he may dispense with the bulkhead and place his electronics and power supplies at any convenient location in the chassis, keeping in mind the cooling capacity that has been provided. The separate compartment configuration is specifically intended for controls applications. The top and bottom are divided so that access to each compartment can be made separately either from the top or the bottom. The front panel contains handles, an A/C ON light and power supply test jacks, one for each voltage provided by the power supplies. The back panel is a flat sheet approximately 195 square inches and is provided with holes only for the on/off circuit breaker and a/c cord. It is left to the user to punch holes for connectors he wishes to use, in whatever configuration best meets his or her specifications. It is expected that the chassis will be fabricated by an outside vendor and be purchased broken down for ease of storage. It will be assembled by the user. With this in mind, Pennuts have been used as much as possible for ease of assembly. It should be noted that the chassis is reversible in that holes are provided to interchange the front and rear panels and the compartments so that connectors will then appear at the front of the rack rather than the rear.

2. The Electronics Compartment

The electronics compartment is designed to contain various configurations of MULTIBUS crates (card cages), and/or DIN spec. Eurocard crates as follows:

- a. Three each, two each, or one each 4 position multibus card crates National Semiconductor Corp. Part No. SBC604. See Illustration #3.
- b. One each, 3 to 15 position card crate, Electronic Solutions Inc. for multibus cards. See Illustration #4.
- c. One each, 4 position card crate and one each card frame DIN spec. to accept 3U/220 mm long cards.

3. The Power Supply Compartment

The package is designed so that one of two optional configurations can be specified by the user and placed in the power supply compartment. The power supplies are installed so that they can be easily replaced if failure occurs by simply unplugging the outputs, inputs and removing four screws.

- a. The first option is a Power One Inc. Model CP255. This is a multi-output supply with suitable outputs for the multibus standard providing positive 5 and 12 volts at 30 and 4.5 amps, and a negative 5 and 12 volts each at 1.75 amps. See Illustration #1.
- b. The second option consists of two separate multi-output supplies. Condor Inc. Model DBB-105W and a Condor Inc., Model BAA-40W. See Illustration #2. One supply provides 5 volts at 12 amps and plus or minus 12 volts at 1.7 amps, or plus or minus 15 volts at 1.5 amps. The second supply provides plus 5 volts at 3 amps, also plus or minus 15 volts at 0.8 amps. The dual supply option is designed to be used where the supplies need to be isolated from each other for the digital oriented multibus and any linear circuits the package may contain, i.e., cards in the DIN spec. card cage. See Illustration #2.
- c. An rf filter Mallory Part No. 10VB1 is part of the package design and is placed immediately after the on/off circuit breaker.

4. Package Cooling

Package cooling is provided by fans, four each for the electronics compartment and two each for the power supplies. These are capable of supporting 200 watts of electronics. Tests have been made with the power supplies under full load and the cooling has proven adequate to keep the internal temperatures of the package such that it meets the temperature specifications of most electronics components. See Appendix 2.

5. Package Documentation

See Appendix 3 for a list of mechanical drawings for the electronic cooling package.

Conclusion

The above described standard electronic package is mechanically strong, gives superior RFI/EMI protection, compares very favorably in terms of cost effectiveness to a purchased package with the same specifications, and meets the needs of packaging electronic controls for the present and future in the Accelerator Department.

Acknowledgments

While the information presented here represents the conclusions of the study group listed in Appendix 1, we acknowledge the many useful suggestions from other interested persons in the Accelerator Department.

Appendix 1

Study Group

R. Frankel
K. Kohler
W. Leonhardt
D. Pope
L. Sadinsky
F. Toldo

Appendix 2

Memo to R. Frankel from W. Leonhardt; re: multibus power supply
heat transfer, 4/19/84.

Appendix 3

Reference Print Numbers

Job Number: D09-1M-15
Drawing Numbers: D09-M-374-3
D09-M-375-4
D09-M-376-3
D09-M-377-3
D09-M-378-3
D09-M-379-3
D09-M-380-3
D09-M-381-3
D09-M-382-3

Appendix 4

Excerpts from "Micro Controller Handbook", Intel Corp., section on "Designing Microcontroller Systems for Electrically Noisy Environments".

mvh

4-19-84

MEMO

TO: R. FRANKEL

FROM: W. LEONHARDT

RE: MULTI-BUS POWER SUPPLY
HEAT TRANSFER

I HAVE RUN AN EXPERIMENT ON THE MULTI-BUS UNIT TO ACCESS THE TEMPERATURE RISE OF THE POWER SUPPLY DURING OPERATION. THE UNIT WAS RUN IN A RACK WITH ALL COVERS ON. POWER RESISTORS WERE CONNECTED TO THE POWER SUPPLY IN A FASHION WHICH CAUSED IT TO RUN AT "HALF CURRENT", A CONDITION DESIGNED TO DISSIPATE THE MAXIMUM POWER. THERMOCOUPLES WERE USED TO MEASURE THE INLET & OUTLET AIR TEMPERATURES AND TEMPERATURES AT FOUR LOCATIONS ON THE POWER SUPPLY. AFTER SEVERAL HOURS OF RUNNING WITH AN INLET TEMPERATURE OF 29°C , THE MAX SUPPLY TEMPERATURE WAS READ AT THE UPPER POWER TRANSISTOR PLATE AS 66°C . THIS THEN REPRESENTS A 37°C RISE OVER AMBIENT WHICH CAN BE SCALED UP CONSERVATIVELY. I ALSO RAN FOR A TIME WITH THE POWER SUPPLY COVER OFF WHICH CAUSED THE POWER SUPPLY MAX TEMP TO RISE TO $69-71^{\circ}\text{C}$ WITH THE SAME INLET TEMP.

PREVIOUS ANALYSIS OF THE CARD SECTION INDICATES THAT IT IS THERMALLY O.K.

cc: E JABLONSKI D DUFF F TADDA

APPENDIX A-1

Figure 8. PCB with Gridded Ground

but you still get a mathematically optimal distribution of currents in the grid structure, such that the current loop produces less magnetic flux than if the return path were restrained to follow any single given ground trace. The key to attaining minimum loop areas for all the current loops together is to let the ground currents distribute themselves around the entire area of the board as freely as possible. They want to minimize their own magnetic field. Just let them.

RF SHIELDING

A time-varying electric field generates a time-varying magnetic field, and vice versa. Far from the source of a time-varying EM field, the ratio of the amplitudes of the electric and magnetic fields is always 377 ohms. Up close to the source of the fields, however, this ratio can be quite different, and dependent on the nature of the source. Where the ratio is near 377 ohms is called the far field, and where the ratio is significantly different from 377 ohms is called the near field. The ratio itself is called the wave impedance, E/H .

The near field goes out about 1/6 of a wavelength from the source. At 1MHz this is about 150 feet, and at 10MHz it's about 15 feet. That means if an EMI source is in the same room with the victim circuit, it's likely to be a near field problem. The reason this matters is that in the near field an RF interference problem could be almost entirely due to E-field coupling or H-field coupling, and that could influence the choice of an RF shield or whether an RF shield will help at all.

In the near field of a whip antenna, the E/H ratio is higher than 377 ohms, which means it's mainly an E-field generator. A wire-wrap post can be a whip antenna. Interference from a whip antenna would be by electric field coupling, which is basically capacitive coupling. Methods to protect a circuit from capacitive coupling, such as a Faraday shield, would be effective against RF

interference from a whip antenna. A gridded-ground structure would be less effective.

In the near field of a loop antenna, the E/H ratio is lower than 377 ohms; which means it's mainly an H-field generator. Any current loop is a loop antenna. Interference from a loop antenna would be by magnetic field coupling, which is basically the same as inductive coupling. Methods to protect a circuit from inductive coupling, such as a gridded-ground structure, would be effective against RF interference from a loop antenna. A Faraday shield would be less effective.

A more difficult case of RF interference, near field or far field, may require a genuine metallic RF shield. The idea behind RF shielding is that time-varying EMI fields induce currents in the shielding material. The induced currents dissipate energy in two ways: I²R losses in the shielding material and radiation losses as they re-radiate their own EM fields. The energy for both of these mechanisms is drawn from the impinging EMI fields. Hence the EMI is weakened as it penetrates the shield.

More formally, the I²R losses are referred to as absorption loss, and the re-radiation is called reflection loss. As it turns out, absorption loss is the primary shielding mechanism for H-fields, and reflection loss is the primary shielding mechanism for E-fields. Reflection loss, being a surface phenomenon, is pretty much independent of the thickness of the shielding material. Both loss mechanisms, however, are dependent on the frequency (ω) of the impinging EMI field, and on the permeability (μ) and conductivity (σ) of the shielding material. These loss mechanisms vary approximately as follows:

$$\text{reflection loss to an E-field (in dB)} \sim \log \frac{\sigma}{\omega \mu}$$

$$\text{absorption loss to an H-field (in dB)} \sim t \sqrt{\omega \sigma \mu}$$

where t is the thickness of the shielding material.

The first expression indicates that E-field shielding is more effective if the shield material is highly conductive, and less effective if the shield is ferromagnetic, and that low-frequency fields are easier to block than high-frequency fields. This is shown in Figure 9.

Figure 9. E-Field Shielding

Figure 10. H-Field Shielding

Copper and aluminum both have the same permeability, but copper is slightly more conductive, and so provides slightly greater reflection loss to an E-field. Steel is less effective for two reasons. First, it has a somewhat elevated permeability due to its iron content, and, second, as tends to be the case with magnetic materials, it is less conductive.

On the other hand, according to the expression for absorption loss to an H-field, H-field shielding is more effective at higher frequencies and with shield material that has both high conductivity and high permeability. In practice, however, selecting steel for its high permeability involves some compromise in conductivity. But the increase in permeability more than makes up for the decrease in conductivity, as can be seen in Figure 10. This figure also shows the effect of shield thickness.

A composite of E-field and H-field shielding is shown in Figure 11. However, this type of data is meaningful only in the far field. In the near field the EMI could be 90% H-field, in which case the reflection loss is irrelevant. It would be advisable then to beef up the absorption loss, at the expense of reflection loss, by choosing steel. A better conductor than steel might be less expensive, but quite ineffective.

A different shielding mechanism that can be taken advantage of for low frequency magnetic fields is the ability of a high permeability material such as mumetal to divert the field by presenting a very low reluctance path to the magnetic flux. Above a few kHz, however, the permeability of such materials is the same as steel.

In actual fact the selection of a shielding material turns out to be less important than the presence of seams, joints and holes in the physical structure of the enclosure. The shielding mechanisms are related to the induction of currents in the shield material, but the currents must be

Figure 11. E- and H-Field Shielding

allowed to flow freely. If they have to detour around slots and holes, as shown in Figure 12, the shield loses much of its effectiveness.

As can be seen in Figure 12, the severity of the detour has less to do with the area of the hole than it does with the geometry of the hole. Comparing Figure 12C with 12D shows that a long narrow discontinuity such as a seam can cause more RF leakage than a line of holes with larger total area. A person who is responsible for designing or selecting rack or chassis enclosures for an EMI environment needs to be familiar with the techniques that are available for maintaining electrical continuity across seams. Information on these techniques is available in the references.

Grounds

There are two kinds of grounds: earth-ground and signal ground. The earth is not an equipotential surface, so earth ground potential varies. That and its other electrical properties are not conducive to its use as a return conductor in a circuit. However, circuits are often connected to earth ground for protection against shock hazards. The other kind of ground, signal ground, is an arbitrarily selected reference node in a circuit—the node with respect to which other node voltages in the circuit are measured.

SAFETY GROUND

The standard 3-wire single-phase AC power distribution system is represented in Figure 13. The white wire is earth-grounded at the service entrance. If a load circuit has a metal enclosure or chassis, and if the black wire develops a short to the enclosure, there will be a shock hazard to operating personnel, unless the enclosure itself is earth-grounded. If the enclosure is earth-grounded, a

4-3

Figure 12. Effect of Shield Discontinuity on Magnetically Induced Shield Current

short results in a blown fuse rather than a "hot" enclosure. The earth-ground connection to the enclosure is called a safety ground. The advantage of the 3-wire power system is that it distributes a safety ground along with the power.

Note that the safety-ground wire carries no current, except in case of a fault, so that at least for low frequencies it's at earth-ground potential along its entire length. The white wire, on the other hand, may be several volts off ground, due to the IR drop along its length.

SIGNAL GROUND

Signal ground is a single point in a circuit that is designated to be the reference node for the circuit. Commonly, wires that connect to this single point are also referred to as "signal ground." In some circles "power supply common" or PSC is the preferred terminology for these conductors. In any case, the manner in which these wires connect to the actual reference point is the basis of distinction among three kinds of signal-ground wiring methods: series, parallel, and multipoint. These methods are shown in Figure 14.

The series connection is pretty common because it's simple and economical. It's the noisiest of the three, however, due to common ground impedance coupling between the circuits. When several circuits share a ground wire, currents from one circuit, flowing through the finite impedance of the common ground line, cause variations in the ground potential of the other circuits. Given that the currents in a digital system tend to be spiked, and that the common impedance is mainly inductive reactance, the variations could be bad enough to cause bit errors in high current or particularly noisy situations.

The parallel connection eliminates common ground impedance problems, but uses a lot of wire. Other disadvantages are that the impedance of the individual ground lines can be very high, and the ground lines themselves can become sources of EMI.

Figure 13. Single-Phase Power Distribution

Application Data Including:

1. Schematic
2. Parts List
3. Specification
4. Outline & Mounting Drawing
5. General User Information

MODEL

CP255

SPECIFICATIONS

INPUT: 100/115/215/230 VAC $\pm 10\%$ 47-63HZ
 OUTPUT: V I OVP $\pm$.4
 +5V 30A 6.2 $\pm$.4
 -5V 1.75A -6.2 $\pm$.4
 +12V 4.5 A 15 $\pm$ 1
 -12V 1.75A 15 $\pm$ 1

ADJUSTMENT RANGE: $\pm 5\%$ min.
 LINE REGULATION: $\pm 0.1\%$ for 10% line change
 LOAD REGULATION: $\pm 0.1\%$ for 50% load change
 RIPPLe AND NOISE: 10mv pk-pk
 TRANSIENT RESPONSE: Less than 50 u sec for 50% load change
 REMOTE SENSING: Provided on +5V at connector P-8.
 STABILITY: $\pm 0.05\%$ for 8 hours after 30 min. warm-up
 AMBIENT TEMP: 0°C to 70°C with 70 CFM moving air
 TEMP. COEFFICIENT: -0.02% per $^{\circ}\text{C}$ max.

SPECIAL OUTPUTS

1. Power Fail (AC low)
Provides a TTL active high signal when AC line fails. Signal is activated at approx. 98/196 VAC and reset at approx. 104/208 VAC. (Open collector output device).
2. Storage
After "AC fail" all outputs will remain in regulation a minimum of 7.5m sec (115 VAC line input).

ADDITIONAL INFORMATION

This power supply is also available as a CP255-1. The only difference is connector P-2 which is made a 5-pin (Molex 03-09-2052) connector instead of the standard 4-pin connector supplied with the CP255. The 5-pin AC connector allows all jumpering for input changes to be done at the connector without removing and rewiring the transformer.
 NOTE: Intel uses the 4-wire scheme.
 National Semiconductor uses the 5-wire scheme.

OPTIONAL TRANSFORMER CONNECTIONS

Range	Input	Input Source	Input Return	Connections Required P2	Fusing
103.5-125.5	115	1	2	1-3, 2-4	5A
207-253	230	1	4	2-3	5A
193.5-236.5	215	5	4	2-3	2.5A
90-110	100	5	2	1-3*, 2-4	2.5A

*For 100/215 VAC operation, move gray wire from terminal 1 to terminal 5. (For 100 VAC operation, terminal 1 must be jumpered to terminal 3 at the transformer).

1 GRY

5 GRY

2 RED

3 ORN

4 WHT

*Jumpered at XFMR

CONNECTOR INFORMATION

P6; P8
Molex

Molex

09-50-7071-housing
 08-56-0106-pin
 15-04-0219-key

03-09-2042-housing
 02-09-2118-pin

P8U

P8L

P6U

P6L

P2

Weight: 21 lbs.

2

POWER-ONE CP 255

C1,2,3	64000/15	CAPACITOR ELECT	105-10030
C4,6	1/50	ELECT	101-10111
C5	.01V100	MYLAR	104-10095
C7,8	4000/15	ELECT	102-10157
C9	.1/100	MYLAR	104-10094
C10	220/16	CAPACITOR ELECT	101-10107
CP 1,2	AT31	DIODE BRIDGE	140-10254
CR 3,7	1N472A	ZENER	112-10336
CR 4,6,7	1N4721	3A, 100V	111-10252
CR 9	MA 750	DIODE 6A, 50V	111-10256
SCR 1,3	50303L53	SCR 3A, 30V	116-10258
SCR 2	1N4644 H	SCR 20A, 25V	116-10257
Q1	2N4055	TRANSISTOR	171-10263
Q2,3,4,5,6	2N2355	TRANSISTOR	171-10243
Q7	2N2307A	TRANSISTOR	172-10248
Q8	2N3055	TRANSISTOR	171-10242
U1,2	11A 723	IC VOLTAGE REGULATOR	321-10679
U1,2	11A 723	IC VOLTAGE REGULATOR	130-10287
R1,14,24,31	2.2 K	RESISTOR 1/4W 5% CF	151-10373
R2,3,12,23,24,25	82 Ω		151-10333
R3,4,5,6,7,34	2.7 Ω		151-10330S
R8,9,10,11,12	2.2 Ω		151-10325
R16,27,18,21	6.8 Ω	5% CF	151-10313
R20,30	2.2 K	5% MF	152-10513
R33	330 Ω	1/4W 5% CF	151-10353
R37	.22 Ω	RESISTOR 2W 10% BWH	158-10079
R13,14,35	1.5 K	POTENTIOMETER	155-10086
T1		TRANSFORMER (REF)	082-13909
PCB		P.C. BOARD	505-13434

INSTALL SOCKET FOR U1,2.
R17 MAY BE TRIMMED IN TEST TO HELP SET DVP TO SPECS.
MEASURE Q7 BODY IS WITHIN .V_{BE} OF PCB.
MINIMUM VALUE FOR C8 IS 9000/15V. ANYTHING LESS IS NOT
TESTABLE. OTHERWISE SPECIFIED

PRODUCTION NOTES:

1. SET PP TO 10V HIGH AT 10VAC
WITH +12V AND +5V FULLY LOADED.

C1,2,3	1/50	CAPACITOR	ALUM ELECT	101-10111
C4,6	7500/35			102-10096
C9	330/35			101-10109
C10	5000/35			102-10095
C15	100/35	ALUM ELECT		101-10110
C1,4,6	1/50	MYLAR		104-10095
C15	.01V100	CAPACITOR, MYLAR		104-10092
CR 1,2	MA 750	DIODE 1A 800V		402-13420
CR 2,5	MA 750			111-10251
CR 3,7	1N4721	3A 100V		112-10256
CR 3,11	1N4658	ZENER		112-10059
Q1		DIODE ZENER		
Q2,3	50303L53	SCR 3A		162-10263
Q4,2	1N4658	SCR 1A		111-10252
Q1	1N4721	TRANSISTOR		171-10243
Q2	2N4055			172-10248
Q3,4,6	2N2355			171-10242
Q5	2N2307	TRANSISTOR		172-10248
R1	2.2 K	RESISTOR 1/4W 5% CF		151-10377
R2,3,12,23,24,25	82 Ω			151-10333
R3,4,5,6,7,34	2.7 Ω			151-10330S
R8,9,10,11,12	2.2 Ω			151-10325
R16,27,18,21	6.8 Ω	5% CF		151-10313
R20,30	2.2 K	5% MF		152-10513
R33	330 Ω	1/4W 5% CF		151-10353
R37	.22 Ω	RESISTOR 2W 10% BWH		158-10079
R13,14,35	1.5 K	POTENTIOMETER		155-10086
T1		TRANSFORMER (REF)		082-13909
PCB		P.C. BOARD		505-13434

4811 CALLE ALTO
CAMARILLO, CALIF. 93010
(805) 484-2851

Information contained;

1. Schematic
2. Parts List
3. Specifications
4. Outline and Mounting
5. General User Information

MODEL

DBB-105W

4811 CALLE ALTO
CAMARILLO, CALIF. 93010
(805) 484-2851

APPLICATION DATA

REV A
SIZE 11297
DWG NO C
SCALE 1 OF 1

SPECIFICATIONS

AC Input: 115/230vac $\pm 10\%$ 47-440Hz.
(Derate output current 10% for 50Hz Operation.)

DC Output: Refer to Voltage/Current Rating Chart. Voltage adjustable $\pm 5\%$ minimum.

Input Fusing: Refer to AC Connection Table.

Line Regulation: $\pm 0.05\%$ for 10% input change.

Load Regulation: $\pm 0.05\%$ for 50% load change.

Output Ripple: 3.0mv Pk-Pk maximum, 0.4mv RMS.

Transient Response: 30 μ seconds for 50% load change.

Short Circuit and Overload Protection: Automatic current limit/foldback.

Reverse Voltage Protection: Provided on Dual and Triple output units.

Remote Sensing: Provided on outputs above 15watts, open sense lead protection built-in.

Stability: $\pm 0.05\%$ for 24hours after warm-up.

Temperature Rating: 0°C to 50°C full rated, derated linearly to 40% at 70°C.

Temperature Coefficient: $\pm 0.02\%/^{\circ}\text{C}$ maximum, 0.002%/°C typical.

Cooling: Units are full rated 50°C in free air, must be derated or fan cooled when mounted in confined area.

Efficiency: 5V units-45%, 12 and 15V units - 55%, 20 and 24V units - 60% at nominal input, full load on output.

Vibration: Per Mil-Std-810B, Method 514, Procedure I, curve AB (to 50Hz).

Shock: Per Mil-Std-810B, Method 516, Procedure V.

AC CONNECTION TABLE

FOR USE AT	115 VAC	230 VAC
JUMPER	1 & 3, 2 & 4	2 & 3
APPLY AC AT	1 & 4	1 & 4
FUSE INPUT AT	3.0 AMPS	1.5 AMPS

VOLTAGE/CURRENT RATING CHART

MODEL	OUTPUT RATING
DBB-105W	5V. AT 12A. W/OVP OVP SET AT 6.2 $\pm$.4V.
	$\pm 12\text{V. AT } 1.7\text{A. OR}$ $\pm 15\text{V. AT } 1.5\text{A.}$

-12/-15V. USEABLE AT -5V. AT 0.7A. BY JUMPERING E1 TO E2.

2 YEAR GUARANTEE

CONDOR will repair or replace any power supply of its manufacture that does not perform to published specifications as a result of defective materials or workmanship for a period of 2 years from date of original purchase. No other obligations or liabilities are implied or expressed. Returns must be freight prepaid.

DC OUTPUTS

DBB CASE

UNIT WEIGHT: 11 lbs.

CONDOR INC.	
ASSEMBLY / OUTLINE & MOUNTING	
DBB-105W	
SIZE	DWG NO
D	11236
SCALE 1:1	SHEET 1 OF 1

REF. DES.	D2-12	CONDOR P/N	QTY.	D5-12/OVP	CONDOR P/N	QTY.	DESCRIPTION
CI, 6,7	1000/16	101-10108	3	1000/16	101-10108	3	CAPACITOR, ALUM., ELECT.
C3				10/25	101-10114	1	ALUM., ELECT.
C4	10/25	101-10114	1	10/25	101-10114	1	ALUM., ELECT.
C5	64000/15	103-10030	1	64000/15	103-10030	1	ALUM., ELECT.
C2	2033/100	104-10092	1	2033/100	104-10092	1	CAPACITOR, MYLAR
CR2	1N5401	111-10252	1	1N5401	111-10252	1	DIODE, RECT., 3A., 100V.
CR3	R711A	140-10003	1	R711A	140-10003	1	BRIDGE
CR4,5	1N4003	111-10251	2	1N4003	111-10251	2	DIODE, RECT., 1A., 200V.
CR6,7	1N4003	111-10251	2	1N4003	111-10251	2	DIODE, RECT., 1A., 200V.
SCR1							RECT., ZENER, 5.6V.
Q1	2N6055	171-10263	1	2N6055	171-10263	1	XSTR., DARLINGTON, NPN
Q2	12500-5	171-10241	1	12500-5	171-10241	1	XSTR., POWER, NPN
Q3,4	12505-2	171-10262	2	12505-2	171-10262	2	XSTR., POWER, NPN
R1	47 Ω	151-10333	1	180 Ω	151-10347	1	RESISTOR, 1/2W., 5%, C.R.
R2		151-		47 Ω	151-10333	1	
R3,5,7	6.8 Ω	151-10313	3	6.8 Ω	151-10313	3	
R6		151-		180 Ω	151-10347	1	
R9,16,18	2.7 Ω	151-10305	3	2.7 Ω	151-10305	3	
R10	1.6K	151-10370	1	2.2K	151-10373	1	
R11	4.7K	151-10361	1	2.2K	151-10373	1	
R12	1K	151-10365	1	2.2K	151-10373	1	
R14	47 Ω	151-10333	1	47 Ω	151-10333	1	
R15	2.2K	151-10373	1	2.2K	151-10373	1	
R17,19	3.9 Ω	151-10307	2	15 Ω	151-10321	2	
R4	4.7K	152-10521	1	1.6K	152-10510	1	5%, C.F.
		152-		152-	152-		1%, M.F.
		152-		152-	152-		1%, M.F.
		158-		158-	158-		1/2W., 1%, M.F.
R6,13	1.5K	155-10085	2	1.5K	155-10085	2	RESISTOR, 2W., 10%, W.W.
							POTENTIOMETER, 2W., W.W., HORZ.
U1	Ua 723	130-10287	1	Ua 723	130-10287	1	L.C. VOLTAGE REGULATOR
T1	1118R	082-11186	1	11192	082-11192	1	TRANSFORMER, POWER
PCB	11184	505-11184	1	11184	505-11184	1	PRINTED CIRCUIT BOARD
HEATSINK CHASSIS	11003	412-11003	1	11003	412-11003	1	SPACER, ROUND 1" x 1/4"
							CHASSIS, ALUMINUM

PRODUCTION NOTES:
1) SCR1 TO BE HEATSINKED.

AC CONNECTION TABLE	
FOR USE AT	115 VAC 230 VAC
JUMPER	103,284 2 83
APPLY AC AT	18.4 18.4
FUSE INPUT AT	2.0AMPS 1.0AMPS

REF. DES.	BB15	CONDOR P/N	QTY.	CC15	CONDOR P/N	QTY.	DESCRIPTION
CI,2	1007/35	101-10110	2	1007/35	101-10110	2	CAPACITOR, ALUM., ELECT.
C9,10	3300/35	102-10099	2	3300/35	102-10099	2	ALUM., ELECT.
CI1,12				3300/35	102-10099	2	ALUM., ELECT.
C3	1/100	104-10094	1	1/100	104-10094	1	CAPACITOR, MYLAR
C4,13	01/100	104-10095	2	01/100	104-10095	2	CAPACITOR, MYLAR
CR3,4	1N4003	111-10251	2	1N4003	111-10251	2	DIODE, RECT., 200V 1A.
CR5,6,7,8,9	1N5401	111-10252	5	1N5401	111-10252	5	DIODE, RECT., 100V, 3A.
CR1,2							RECT., ZENER
SCR1,2							DIODE, ZENER
Q1	2N6053	171-10263	1	2N6055	171-10263	1	XSTR., DARLINGTON, NPN
Q2	12500-5	171-10241	1	12500-5	171-10241	1	XSTR., POWER, NPN
Q3							XSTR., POWER
Q4	2N2905A	172-10246	1	2N2905A	172-10246	1	XSTR., SIGNAL, 60V.
Q5	2N2905A	172-10246	1	2N2905A	172-10246	1	XSTR., SIGNAL, 40V.
R1,2,20,35,38	1K	151-10365	5	1K	151-10365	5	RESISTOR, 1/2W., 5%, C.R.
R3,4	47 Ω	151-10333	2	47 Ω	151-10333	2	
R8,13,16	6.8 Ω	151-10313	4	6.8 Ω	151-10313	4	
R8,11	180 Ω	151-10347	2	180 Ω	151-10347	2	
R22	1.6K	151-10370	1	1.6K	151-10370	1	
R25,31	4.7K	151-10361	3	4.7K	151-10361	3	
R26	300 Ω	151-10352	1	300 Ω	151-10352	1	
R29	2.7 Ω	151-10305	1	2.7 Ω	151-10305	1	
R30	270 Ω	151-10351	1	270 Ω	151-10351	1	
R32,33,36,37	330 Ω	151-10353	4	330 Ω	151-10353	4	
R34		151-			151-		5%, C.F.
		151-			151-		1%, M.F.
R7,10	1.2K	152-10507	2	1.2K	152-10507	2	1%, M.F.
R19	2.7K	152-10515	1	2.7K	152-10515	1	1%, M.F.
R21	2.2K	152-10513	1	2.2K	152-10513	1	1/2W., 1%, M.F.
R27,28	22 Ω	158-10079	2	12 Ω	158-10077	2	RESISTOR, 2W., 10%, W.W.
R8,12	1.9K	155-10085	2	1.5K	155-10085	2	POTENTIOMETER, 2W., W.W.
U1,2	Ua 723	130-10287	2	Ua 723	130-10287	2	L.C. VOLTAGE REGULATOR
T1	11265	082-11265	1	11375	082-11375	1	TRANSFORMER, POWER
PCB	11263	505-11263	1	11263	505-11263	1	PRINTED CIRCUIT BOARD
CHASSIS	11007	412-11007	1	11006	412-11006	1	CHASSIS, ALUMINUM

AC CONNECTION TABLE	
FOR USE AT	115 VAC 230 VAC
JUMPER	183,284 2 83
APPLY AC AT	18.4 18.4
BB FUSE INPUT AT	1.0AMPS 0.5AMPS
CC FUSE INPUT AT	2.0AMPS 1.0AMPS

PRODUCTION NOTES:
1) ON 'CC' USE RTV TO SECURE CI1,12.

4880 ADOHR LANE
CAMARILLO, CALIF. 93010
(805) 484-2851

Information contained;

1. Schematic
2. Parts List
3. Specifications
4. Outline and Mounting
5. General User Information

MODEL

BAA-40W

4880 ADOHR LANE
CAMARILLO CALIF 93010
(805) 484-2851

APPLICATION DATA

REV. A
SHEET 1 OF 1
11316
SCALE 1:1

SPECIFICATIONS

AC Input: 115/230vac $\pm$ 10% 47-440Hz.
(Derate output current 10% for 50Hz Operation.)

DC Output: Refer to Voltage/Current Rating Chart. Voltage adjustable $\pm$ 5% minimum.

Input Fusing: Refer to AC Connection Table.

Line Regulation: $\pm$ 0.05% for 10% input change.

Load Regulation: $\pm$ 0.05% for 50% load change.

Output Ripple: 3.0mv Pk-Pk maximum, 0.4mv RMS.

Transient Response: 30 μ -seconds for 50% load change.

Short Circuit and Overload Protection: Automatic current limit/foldback.

Reverse Voltage Protection: Provided on Dual and Triple output units.

Remote Sensing: Provided on outputs above 15watts, open sense lead protection built-in.

Stability: $\pm$ 0.05% for 24hours after warm-up.

Temperature Rating: 0°C to 50°C full rated, derated linearly to 40% at 70°C.

Temperature Coefficient: $\pm$ 0.02%/°C maximum, 0.002%/°C typical.

Cooling: Units are full rated 50°C in free air, must be derated or fan cooled when mounted in confined area.

Efficiency: 5V units-45%, 12 and 15V units - 55%, 20 and 24V units - 60% at nominal input, full load on output.

Vibration: Per Mil-Std-810B, Method 514, Procedure I, curve AB (to 50Hz).

Shock: Per Mil-Std-810B, Method 516, Procedure V.

AC CONNECTION TABLE

FOR USE AT	115 VAC	230 VAC
JUMPER	1 8 3, 2 8 4	2 8 3
APPLY AC AT	1 8 4	1 8 4
FUSE INPUT AT	1.0 AMPS	0.5 AMPS

VOLTAGE/CURRENT RATING CHART

MODEL	OUTPUT RATING
BAA-40W	5V. AT 3.0A W/OVP OVP SET AT 6.2 $\pm$.4V. $\pm$ 12V. AT 1.0A OR $\pm$ 15V. AT 0.8A.

-12/-15V. USEABLE AT -5V. AT 0.4A. BY JUMPERING E1 TO E2.

2 YEAR GUARANTEE

CONDOR will repair or replace any power supply of its manufacture that does not perform to published specifications as a result of defective materials or workmanship for a period of 2 years from date of original purchase. No other obligations or liabilities are implied or expressed. Returns must be freight prepaid.

DC OUTPUTS

BAA CASE

UNIT WEIGHT: 5 lbs

11/15/78 3

CHASSIS OUTLINE
BLC MODULAR CARD CAGE

.188 DIA THRU
8 HOLES

.120 DIA x .50 DEEP
8 HOLES

National Semiconductor Corporation
2900 Semiconductor Drive
Santa Clara, California 95051

A	140305378	A
SCALE .25:1	SHEET 2 OF 2	

ILLU ST. #4

①

Electronic Solutions

5780 Chesapeake Ct., San Diego, CA 92123
(714) 292-0242 (800) 854-7086
Telex II (TWX): 910-335-1169

MULTI-CAGE®

Card Cages for the Multibus*

3 TO 26 SLOTS AVAILABLE

Designed To Save You Space

- Accepts iSBX* cards
- Accepts three-level w-w cards.
- Mates directly to Intel's iSBC* Card Cages
- Includes backplane power supply connectors
- Has smooth, easy insertion nylon card guides
- Has extensive ground plane for noise reduction

- Lightweight black anodized aluminum construction allows easy accessory mounting
- Has mounting provisions for -5V regulator (LM 320T-5.0)
- Has mounting provisions for reset switch (C&K 8121R)
- Rack mount models with vertical or horizontal slots

DESCRIPTION

The **MULTI-CAGE®** card cage with mother board backplane is designed to be 100% compatible with Intel's iSBC* 80 cards and card cages. All **MULTI-CAGE®** card cages (except the SBC 614) have resistor termination networks for bus signals. The SBC 614 has no termination network but has a female bus expansion connector added. All **MULTI-CAGES®** come with a male expansion connector. This connection may be solder plated (no suffix) or gold plated (G suffix).

More Room

You get more room for extra cards without increasing overall size, because our design gives you greater inside dimensions.

More Reliability

All cages are constructed of sturdy, durable anodized aluminum with a single mother board backplane ... a concept that increases reliability and minimizes interconnections.

RACK MOUNTING TOO!

More Models

We have more models than all our competitors combined. Choose a cage with 3, 4, 5, 6, 7, 8, 9, 12, 14, 15, 16, 20, 24 or 26 slots for the right solution to your problem. We have models with either 0.6" or 0.75" card centers and can even accommodate wirewrap and iSBX cards.

All models are electrically and dimensionally interchangeable with Intel's iSBC-80® Cages.

More Warranty

A three year warranty is your assurance of quality.

Electronic Solutions

5780 Chesapeake Ct., San Diego, CA 92123
(714) 292-0242 (800) 854-7086
Telex II (TWX): 910-335-1169

Multibus, iSBX and iSBC are trademarks of the Intel Corporation.
MULTI-CAGE® is a trademark of Electronic Solutions.

STANDARD MODELS

DIMENSION TABLE

Part No.		A	B	C	D*	
.6" Center	.75" Center				.6" Center	.75" Center
ESBC 604	SBC 753	3.34 in. (84.84) mm.	2.50 in. (63.5) mm.	2.750 in. (69.85) mm.	.61 in. (15.49) mm.	.91 in. (23.11) mm.
ESBC 614	SBC 753	3.34 in. (84.84) mm.	2.50 in. (63.5) mm.	2.750 in. (69.85) mm.	.61 in. (15.49) mm.	.91 in. (23.11) mm.
*SBC 604A	—	3.34 in. (84.84) mm.	2.50 in. (63.5) mm.	2.750 in. (69.85) mm.	.96 in. (24.38) mm.	—
SBC 605	SBC 754	3.94 in. (100.08) mm.	3.1 in. (78.74) mm.	3.35 in. (85.09) mm.	.61 in. (15.49) mm.	.76 in. (19.3) mm.
SBC 606	SBC 755	4.54 in. (115.32) mm.	3.7 in. (93.98) mm.	3.95 in. (100.33) mm.	.61 in. (15.49) mm.	.61 in. (15.49) mm.
SBC 608	SBC 757	6.68 in. (169.67) mm.	5.84 in. (148.34) mm.	6.09 in. (154.69) mm.	.95 in. (24.13) mm.	1.25 in. (31.75) mm.
SBC 6012	SBC 7512	10.02 in. (254.51) mm.	9.18 in. (233.17) mm.	9.43 in. (239.52) mm.	.69 in. (17.53) mm.	.84 in. (21.34) mm.
SBC 6014	SBC 7512	10.02 in. (254.51) mm.	9.18 in. (233.17) mm.	9.43 in. (239.52) mm.	.69 in. (17.53) mm.	.84 in. (21.34) mm.
SBC 6015	SBC 7512	10.02 in. (254.51) mm.	9.18 in. (233.17) mm.	9.43 in. (239.52) mm.	.69 in. (17.53) mm.	.84 in. (21.34) mm.
SBC 6016	SBC 7516	13.36 in. (339.34) mm.	12.52 in. (318.00) mm.	12.77 in. (324.36) mm.	1.03 in. (26.16) mm.	1.18 in. (29.97) mm.
SBC 6020	SBC 7516	13.36 in. (339.34) mm.	12.52 in. (318.00) mm.	12.77 in. (324.36) mm.	1.03 in. (26.16) mm.	1.18 in. (29.97) mm.
SBC 6024	SBC 7521	16.7 in. (424.18) mm.	15.86 in. (402.84) mm.	16.11 in. (409.19) mm.	.77 in. (19.56) mm.	.77 in. (19.56) mm.
SBC 6026	SBC 7521	16.7 in. (424.18) mm.	15.86 in. (402.84) mm.	16.11 in. (409.19) mm.	.77 in. (19.56) mm.	.77 in. (19.56) mm.

*This Dimension indicates clearance from the inside wall of the cage to the first card center.

HORIZONTAL RACK MOUNT MODELS

STANDARD MODELS

Models with .6 inch Card Centers				
Model	No. of Slots	No. of iSBX cards	No. of w-w cards	Price (1-4)†
ESBC 604	4	0	1	\$ 195
ESBC 614G	4	0	1	220
SBC 604A	4	1	0	195
SBC 605	5	0	1	245
SBC 606	6	0	1	295
SBC 608	8	2	2	395
SBC 609	9	1	1	445
SBC 6012	12	3	4	645
SBC 6014	14	1	2	745
SBC 6015	15	0	1	795
SBC 6016	16	5	5	845
SBC 6020	20	1	1	1045
SBC 6024	24	2	3	1245
SBC 6026	26	0	1	1345

Models with .75 inch Card Centers				
Model	No. of Slots	No. of iSBX cards	No. of w-w cards	Price (1-4)†
SBC 753	3	0	1	\$ 190
SBC 754	4	0	1	235
SBC 755	5	0	1	270
SBC 757	7	1	1	380
SBC 7512	12	0	1	705
SBC 7516	16	1	1	925
SBC 7521	21	0	1	1200

†For gold expansion connector add \$10 and use suffix G after Model #.

HORIZONTAL RACK MOUNTS

Models with .6 inch Card Centers				
Model	No. of Slots	No. of iSBX cards	No. of w-w cards	Price (1-4)†
ESBC 604H	4	0	1	\$ 325
SBC 604AH	4	1	0	325
SBC 605H	5	0	1	395
SBC 606H	6	0	1	445
SBC 608H	8	2	2	545
SBC 609H	9	1	1	595

Models with .75 inch Card Centers				
Model	No. of Slots	No. of iSBX cards	No. of w-w cards	Price (1-4)†
SBC 753H	3	0	1	\$ 320
SBC 754H	4	0	1	385
SBC 755H	5	0	1	420
SBC 757H	7	1	1	530

†For gold expansion connector add \$10 and use suffix G after Model #.

VERTICAL RACK MOUNTS

Models with .6 inch Card Centers				
Model	No. of Slots	No. of iSBX cards	No. of w-w cards	Price (1-4)†
SBC 6012V	12	4	4	\$ 895
SBC 6014V	14	2	2	995
SBC 6015V	15	1	1	1045
SBC 6016V	16	5	5	1095
SBC 6020V	20	1	1	1295
SBC 6024V	24	3	3	1495
SBC 6026V	26	0	1	1595

Models with .75 inch Card Centers				
Model	No. of Slots	No. of iSBX cards	No. of w-w cards	Price (1-4)†
SBC 7512V	12	0	1	\$ 955
SBC 7516V	16	1	1	1175
SBC 7521V	21	0	1	1450

†For gold expansion connector add \$10 and use suffix G after Model #.

P-2 BUS (AUXILIARY BUS)

Printed Circuit Board Only:			Assembled with connectors:		
Part Number	Number of Slots	Price Qty 1-9	Part Number	Number of Slots	Price Qty 1-9
P2-604P-*	4	\$37.00	P2-604C-*	4	\$ 97.00
P2-605P-__	5	38.00	P2-605C-__	5	113.00
P2-606P-__	6	39.00	P2-606C-__	6	129.00
P2-608P-__	8	40.00	P2-608C-__	8	160.00
P2-609P-__	9	40.00	P2-609C-__	9	175.00
P2-6012P-__	12	55.00	P2-6012C-__	12	235.00
P2-6014P-__	14	55.00	P2-6014C-__	14	265.00
P2-6015P-__	15	55.00	P2-6015C-__	15	280.00
P2-6016P-__	16	69.00	P2-6016C-__	16	309.00
P2-6020P-__	20	69.00	P2-6020C-__	20	369.00
P2-6024P-__	24	74.00	P2-6024C-__	24	434.00
P2-6026P-__	26	74.00	P2-6026C-__	26	464.00

* Use suffix E for PCB based Point-to-Point, or use suffix M for PCB based per Intel Multibus specification 9800683-02

ACCESSORIES

P2 Auxiliary Connectors (wire-wrap):		
EZC 30 DRMD Selective Plated—Gold Contacts only		\$ 7.50 ea.
ESC 30 DRMD Gold Plated Pins		8.90 ea.
P2 Auxiliary Connectors (Solder Tab):		
EZC 30 DTKD Selective Plated—Gold Contacts only		7.50 ea.
09-50-7071	Molex Mating Connectors, with Pins	2.50 ea.
LM 320T-5.0	-5V Regulator	12.00 ea.
8121 R	Reset Switch	8.60 ea.
FMB	Fan Mounting Bracket Kit for SBC 608, 609 and 757	12.00 ea.
MK-4	Spacer Mounting kit to replace rubber feet	3.00 ea.
PPRC-8	Eight Master Parallel Priority Resolution	55.00 ea.
PPRC-16	Sixteen Master Parallel Priority Resolution	70.00 ea.

More Information?

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